Appl. No. 10/749,499 Amdt. dated July 5, 2006 Reply to Office Action of April 5, 2006

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## Amendments to the Specification

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Please replace the paragraph beginning at line 13 of page 7 as follows:

Once properly positioned, polymer layer 24 can be disposed over marker band 20. As described above, polymer layer 24 can flow through holes 22 and fill any void 26 that might otherwise be created between marker band 20 and shaft 12. Accordingly, it may be desirable to use a thermoplastic material (i.e., a material whose viscosity changes with the induction of heat), a thermoplastic-like material, a thermoset material, combinations thereof, or the like for polymer layer 24. Some examples of suitable polymers (including thermoplastics) may include polytetrafluoroethylene (PTFE), ethylene tetrafluoroethylene (ETFE), fluorinated ethylene propylene (FEP), polyoxymethylene (POM), polybutylene terephthalate (PBT), polyether block ester, polyurethane, polypropylene (PP), polyvinylchloride (PVC), polyether-ester (for example, a polyether-ester elastomer such as ARNITEL® available from DSM Engineering Plastics), polyester (for example, a polyester elastomer such as HYTREL® available from DuPont), polyamide (for example, DURETHAN® available from Bayer or CRISTAMID® available from Elf Atochem), elastomeric polyamides, block polyamide/ethers, polyether block amide (PEBA, for example, available under the trade name PEBAX®), silicones, polyethylene (PE), Marlex high-density polyethylene, Marlex low-density polyethylene, linear low density (PET). terephthalate REXELL®), polyethylene polyethylene (for example, polyetheretherketone (PEEK), polyimide (Pl), polyetherimide (PEI), polyphenylene sulfide (PPS), polyphenylene oxide (PPO), polysulfone, nylon, perfluoro(propyl vinyl ether) (PFA), low durometer thermal plastics (e.g., 25-50 Sure D), tungsten loaded thermal plastic compound, bismuth subcarbonate loaded thermal plastic compound, barium sulfate loaded thermal plastic compound, other suitable materials, or mixtures, combinations, copolymers thereof, polymer/metal composites, and the like. In some embodiments, polymer layer 24 can be blended with a liquid crystal polymer (LCP). For example, the mixture can contain up to about 5% LCP. In some embodiments, polymer layer 24 may include multiple segments of polymeric material having desired property variations.

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Please replace the paragraph beginning at line 21 of page 9 as follows:

Figure 7 is another example marker band 320 where holes or slits 322 are disposed at the ends 338a/b of body portion 334. Holes or slits 332 may be defined by, for example, one or more longitudinal deflections defined in ends 338a/b of body portion 334. This embodiment illustrates that slits 322 can be disposed at essentially any position along marker band 320 and still have the desired effects. For example, slits 322 disposed at ends 338a/b allow polymer layer 24 to flow under marker band 320 so as to improve bonding between marker band 320 and shaft 12, as described above.